

Formula 1

A¹

wherein R₁ is an aryl radical with two hydroxyl groups, and the aryl radical can be substituted by one to three lower alkyls, and

an organic solvent,

wherein the epoxy resin and the organophosphorous compound have been compounded at a temperature of 50°C or lower.

A²

8. (Amended) The resin composition according to claim 7, wherein the inorganic filler is aluminum hydroxide.

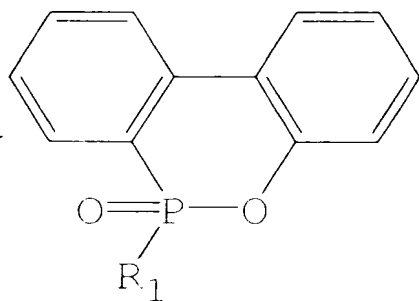
A³

10. (Amended) A prepreg obtainable by impregnating a substrate with the resin composition according to any one of claims 1 to 9 and then drying the substrate impregnated with the resin composition.

11. (Amended) A laminate comprising at least one prepreg according to claim 10 and at least one metal foil.

12. (Amended) A printed wiring plate wherein the resin composition according to any one of claims 1 to 9 is used as an insulating material substrate.

13. (Amended) A method for producing a resin composition comprising:
an epoxy resin,
an amine-type curing agent,
an organophosphorous compound having a structure represented by formula 1:

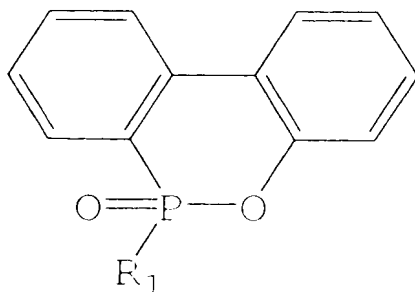


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an organic solvent,
wherein the epoxy resin and the organophosphorous compound are compounded at a temperature of 50°C or lower.

14. (Amended) A method for producing a resin composition comprising:
an epoxy resin,
an amine-type curing agent,

an organophosphorous compound having a structure represented by formula 1:



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wherein R₁ is an aryl radical with two hydroxyl groups, and the aryl radical can be substituted by one to three lower alkyls, and

an organic solvent,

the method comprising:

allowing the epoxy resin and the amine-type curing agent to react in the organic solvent at a temperature of from 80 to 140°C,

whereby bringing the two components into a state where the two components are mutually compatible in the absence of a solvent, and then

compounding the organophosphorus compound to the reaction product at a temperature of 50°C or lower.

17. (Amended) A method producing a laminate, the method comprising arranging at least one metal foil on at least one prepreg prepared by the method according to claim 16, and heating and pressurizing them to laminate together.